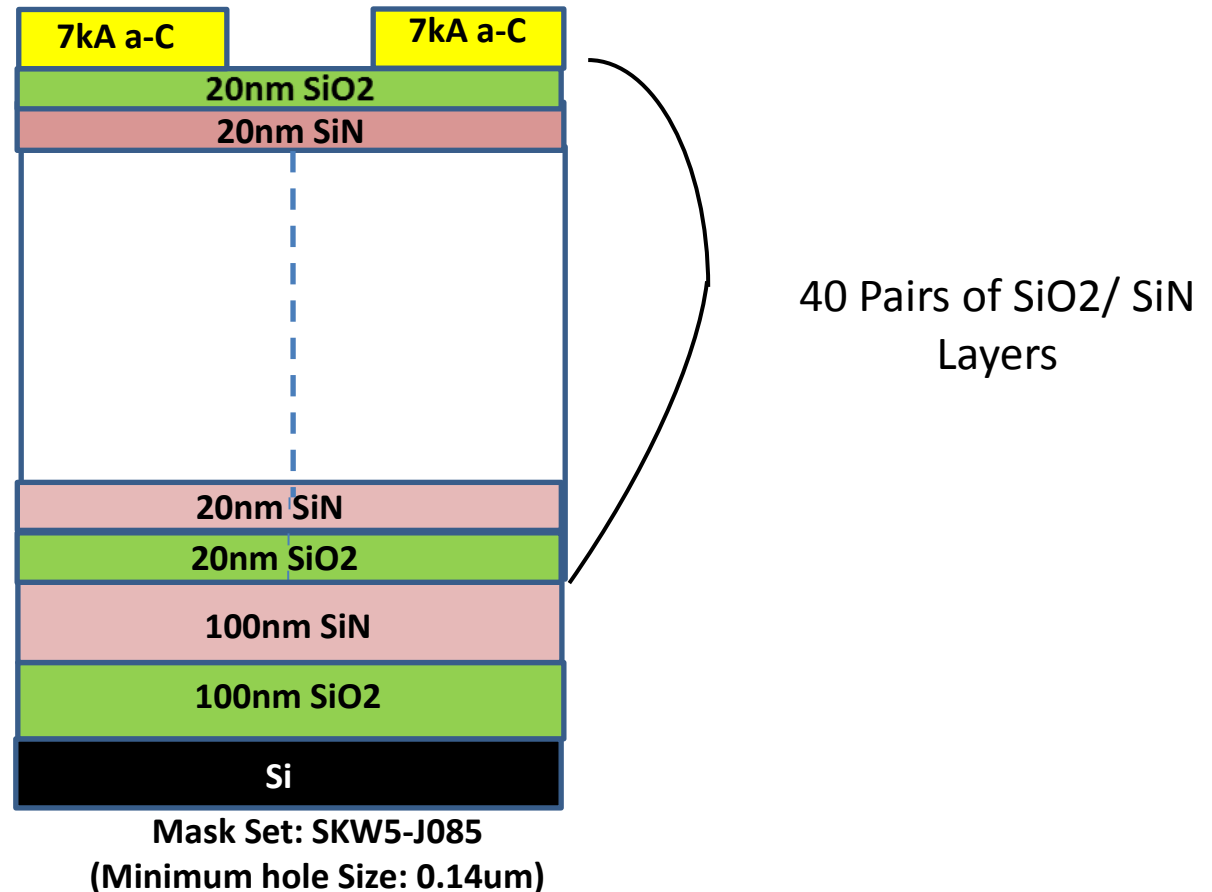


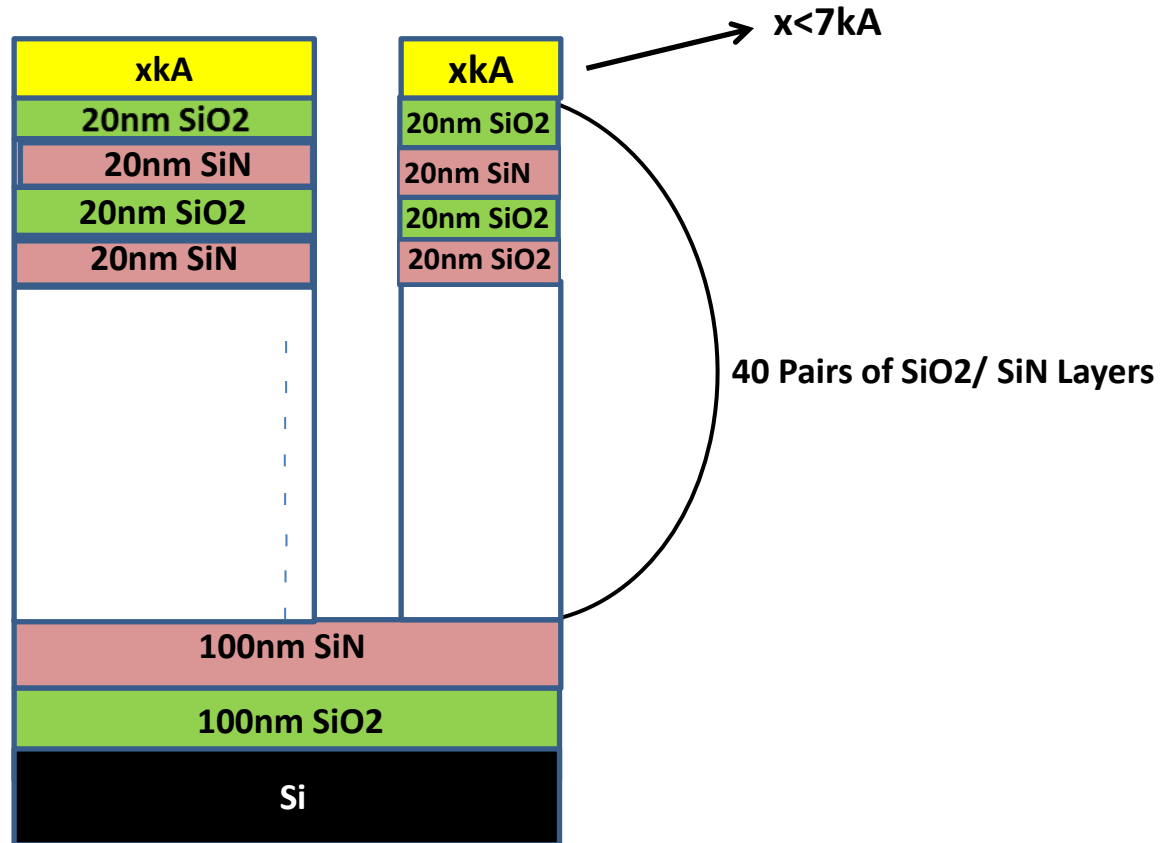
# New 200 mm Patterned Wafers for 3DNAND Flash Memory Process Development

## I. Etch Process Development



# ➤ New 200 mm Patterned Wafers for 3D NAND Flash Memory Process Development

## ➤ II. Deposition and Cleaning Process Development



Mask Set: SKW5-J085  
(Minimum hole Size: 0.14 $\mu$ m)